



Spec No.: DS-70-96-0015 Effective Date: 10/20/2015

Revision: F

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4



1. DESCRIPTION

1.1 Features

■ Current transfer ratio (CTR: MIN. 600% at I_F = 1mA, V_{CE} = 2V)

■ High input-output isolation voltage (V_{iso} = 5,000Vrms)

■ Response time (tr : TYP. $60\mu s$ at $V_{CE} = 2V$, $I_C = 10mA$, $R_L = 100\Omega$)

■ Dual-in-line package :

LTV-815 : 1-channel type LTV-825 : 2-channel type LTV-845 : 4-channel type

■ Wide lead spacing package :

LTV-815M : 1-channel type LTV-825M : 2-channel type

LTV-845M: 4-channel type

Surface mounting package :

LTV-815S: 1-channel type LTV-825S: 2-channel type

LTV-845S: 4-channel type

■ Tape and reel packaging :

LTV-815S-TA: 1-channel type

LTV-815S-TA1 : 1-channel type
LTV-815S-TP : 1-channel type

LTV-825S-TA1: 2-channel type

Safety approval

UL 1577

VDE DIN EN60747-5-5 (VDE 0884-5)

CSA CA5A

Nordic Safety (FIMKO/NEMKO/SEMKO/DEMKO)

■ BSI RoHS Compliance

All materials be used in device are followed EU RoHS directive (No.2002/95/EC).

- ESD pass HBM 8000V/MM2000V
- MSL class1

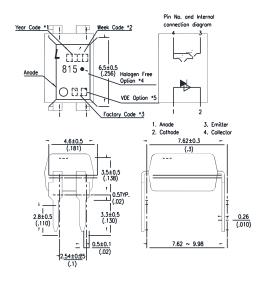
1.2 Applications

- Hybrid substrates that require high density mounting.
- Programmable controllers

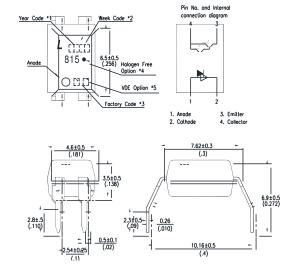


2. PACKAGE DIMENSIONS

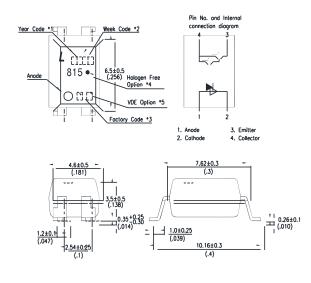
2.1 LTV-815



2.2 LTV-815M



2.3 LTV-815S



Notes:

- 1. Year date code.
- 2. 2-digit work week.
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- "●" for halogen free option.
- 6. "4"or"V" for VDE option.

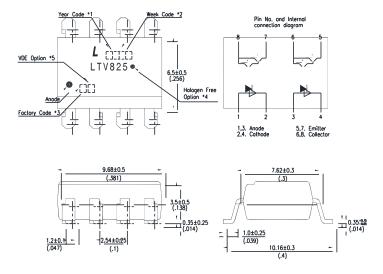
Dimensions in millimeters(inches).



2.4 LTV-825

LTV825 LTV825 Halogen Free Option *4 5,7. Emitter 6.8. Collector 1,3. Anode 2,4. Cathode 1,3. Anode 2,4. Cathode 5,7. Emitter 6,8. Collector 6.9±0.5 (0.272) 2.8±.5 (.110)

2.6 LTV-825S



Notes:

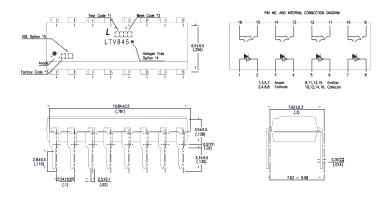
2.5 LTV-825M

- 1. Year date code.
- 2-digit work week.
- 3. Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- Rank shall be or shall not be marked.
- "
 o" for halogen free option.
- VDE option shall be

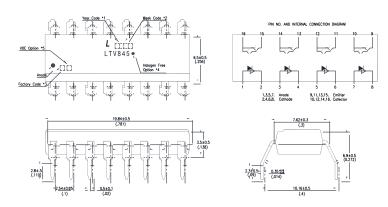
Dimensions in millimeters(inches).



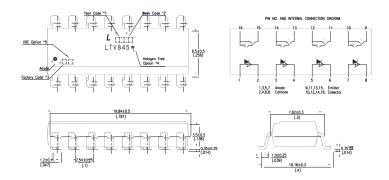
2.7 LTV-845



2.8 LTV-845M



2.9 LTV-845S



Notes:

- 1. Year date code.
- 2. 2-digit work week.
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- "●" for halogen free option.
- 6. VDE option shall be

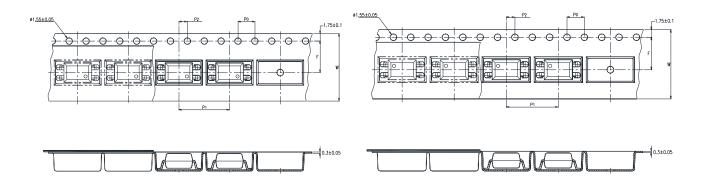




3. TAPING DIMENSIONS

3.1 LTV-815S-TA

3.2 LTV-815S-TA1



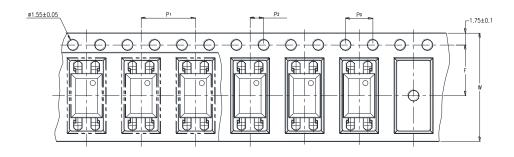
Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P ₀	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	12±0.1 (0.472)

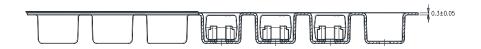
3.3 Quantities Per Reel

Package Type	TA/TA1
Quantities (pcs)	1000



3.4 LTV-815S-TP





Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P ₀	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P ₂	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	8±0.1 (0.472)

3.5 Quantities Per Reel

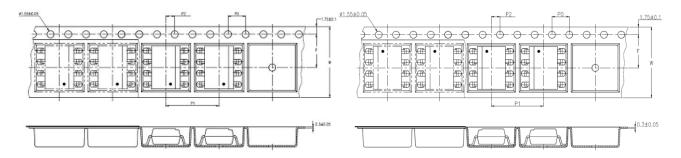
Package Type	TP
Quantities (pcs)	2000





3.6 LTV-825S-TA

3.7 LTV-825S-TA1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P ₀	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P ₂	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	12±0.1 (0.472)

3.8 Quantities Per Reel

Package Type	TA/TA1
Quantities (pcs)	1000



4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
	Forward Current	I _F	50	mA
Input	Reverse Voltage	V_R	6	V
	Power Dissipation		70	mW
	Collector - Emitter Voltage	V _{CEO}	35	V
Output	Emitter - Collector Voltage	V _{ECO}	6	V
Output	Collector Current	Ic	80	mA
	Collector Power Dissipation	Pc	150	mW
	Total Power Dissipation	P _{tot}	200	mW
1.	Isolation Voltage	V _{iso}	5000	V_{rms}
	Operating Temperature	T_{opr}	-30 ~ +110	°C
	Storage Temperature	T_{stg}	-55 ~ +125	°C
2	Soldering Temperature	T _{sol}	260	°C

1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

Parameter		Symbol	Min.	Тур.	Max.	Unit	Test Condition
	Forward Voltage	V _F	_	1.2	1.4	V	I _F =±20mA
Input	Reverse Current	I _R	_	_	10	μА	V _R =4V
	Terminal Capacitance	Ct	_	30	250	pF	V=0, f=1KHz
	Collector Dark Current	I _{CEO}	_	_	1	μΑ	V _{CE} =10V, I _F =0
Output	Collector-Emitter Breakdown Voltage	BV _{CEO}	35	_	_	V	I _C =0.1mA, I _F =0
	Emitter-Collector Breakdown Voltage		6	_	_	V	I _E =10μΑ, I _F =0
	Collector Current	Ic	6	_	75	mA	$I_F=1mA, V_{CE}=2V$
	Current Transfer Ratio	CTR	600	_	7500	%	
	Collector-Emitter Saturation Voltage		_	0.8	1	V	I _F =20mA, I _C =5mA
TRANSFER	Isolation Resistance	R _{iso}	5×10 ¹⁰	1×10 ¹¹	_	Ω	DC500V, 40 ~ 60% R.H.
CHARACTERISTICS	Floating Capacitance	Cf	_	0.6	1	pF	V=0, f=1MHz
	Cut-off Frequency	f _c	1	6	_	kHz	V_{CE} =5V, I_{C} =2mA R_{L} =100 Ω ,-3dB
	Response Time (Rise)	tr	_	60	300	μS	V _{CE} =2V, I _C =10mA
	Response Time (Fall)	tf	_	53	250	μS	R_L =100 Ω ,

1. CTR =
$$\frac{I_C}{I_F} \times 100\%$$



5. CHARACTERISTICS CURVES

Fig.1 Forward Current vs. Ambient Temperature

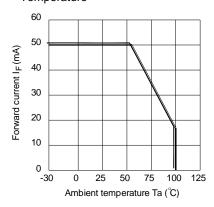


Fig.3 Collector-emitter Saturation Voltage vs. Forward Current

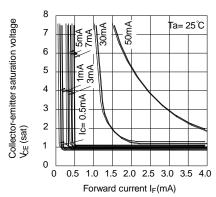


Fig.5 Current Transfer Ratio vs. Forward Current

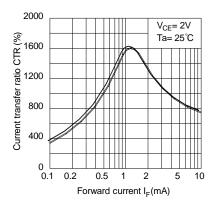


Fig.2 Collector Power Dissipation vs.
Ambient Temperature

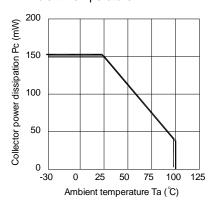


Fig.4 Forward Current vs. Forward Voltage

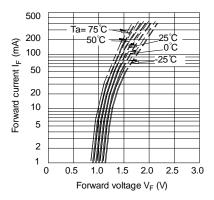


Fig.6 Collector Current vs.

Collector-emitter Voltage

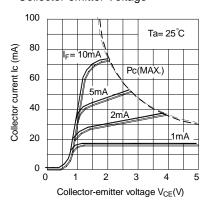




Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

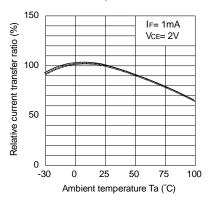


Fig.9 Collector Dark Current vs.
Ambient Temperature

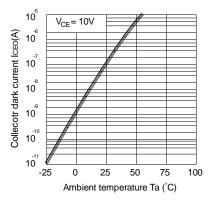


Fig.11 Frequency Response

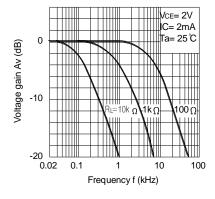


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

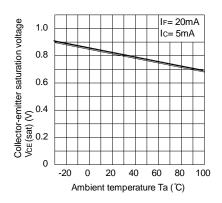
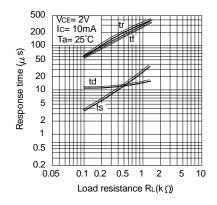
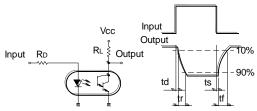


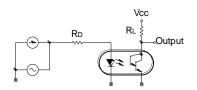
Fig.10 Response Time vs. Load Resistance



Test Circuit for Response Time



Test Circuit for Frequency Response



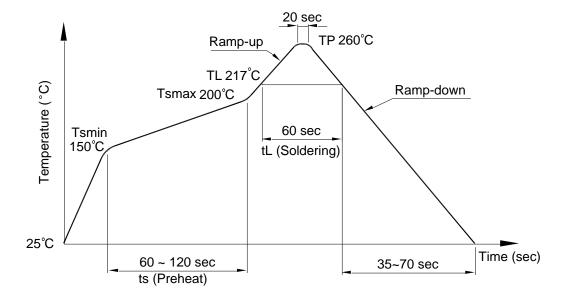


6. TEMPERATURE PROFILE OF SOLDERING

6.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions				
Preheat					
- Temperature Min (T _{Smin})	150°C				
- Temperature Max (T _{Smax})	200°C				
- Time (min to max) (ts)	90±30 sec				
Soldering zone					
- Temperature (T _L)	217°C				
- Time (t _L)	60 sec				
Peak Temperature (T _P)	260°C				
Ramp-up rate	3°C / sec max.				
Ramp-down rate	3~6°C / sec				





6.2 Wave soldering (JEDEC22A111 compliant)

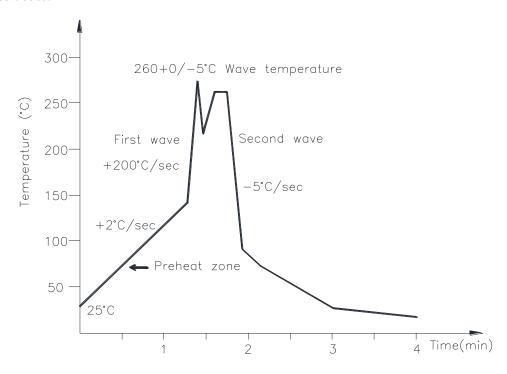
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



6.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

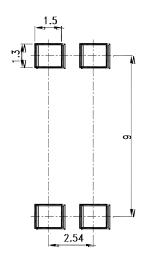
Temperature: 380+0/-5°C

Time: 3 sec max.

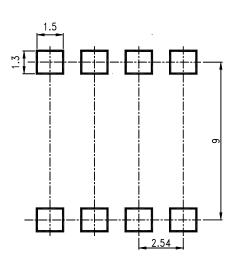


7. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

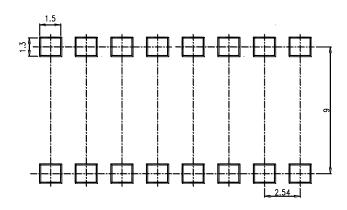
7.1 4 PIN



7.2 8 PIN



7.3 16PIN

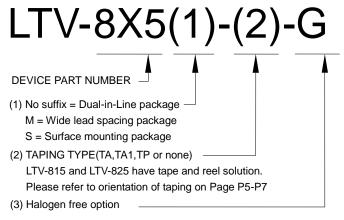


Note:

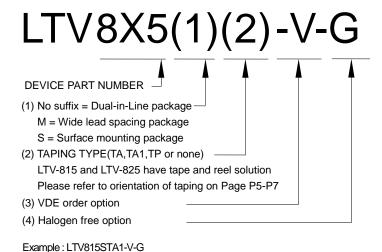
Dimensions in millimeters.



8. Naming rule



Example: LTV-817S-TA1-G



9. Notes:

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.